

Microsemi Corporation

December 15, 2016

Product/Process Change Notification No: 157021

Change Classification: Major

Subject: Assembly Qualification of UTAC Thailand for PoE Products in QFN packages, PD70101ILQ, PD70201ILQ and PD70211ILQ

Description of Change:

Microsemi is qualifying an alternative assembly site for the PoE product family at UTAC, Thailand (UTL). UTL is currently a qualified assembly site for Microsemi.

The BOM changes are listed in the table below.

	Current BOM	UTL BOM
Mold Compound	G770HCD	G700LTD
Die Attach	2700HT/8006NS	590-4HT/8006NS
Wire	PdCu/Au	AuPdCu
Lead Finish	Matte-Tn	PPF

The Moisture Sensitivity Level (MSL) requirement for the products in this package will also be changing from MSL1 to MSL3. Packaging for the associated part numbers will change to dry pack with desiccant, and slightly larger boxes will be used to accommodate this new packing material.

Reason for Change:

The location change is to align with a Corporate Operations subcontractor consolidation initiative. Changing to MSL3 is being done to align with standardized backend packing procedures for QFN/DFN packages across the product group. It will also increase package robustness in reflow.

Application Impact:

There is no impact to the customers' applications since there are no changes to form, fit, function, or product reliability as a result of the move. Receiving departments should be informed that the new boxes may have a slight difference in dimensions, and the material will require MSL3 handling. Datasheets will be updated accordingly.

Method of Identifying Changed Product:

The assembly location is listed on the product package box and tape and reel labels.

Product assembled at the new assembly location will have a new standardized marking format which includes assembly site and production revision identifiers. These identifiers will be in the second line of text in the new marking. See an example below:

Pin1 corner



Products Affected by this Change:

Package	Body Size	Pin Count	Ordering Part number
QFN	5x5	32	PD70101ILQ-TR
QFN	5x5	32	PD70201ILQ-TR
QFN	6x6	36	PD70211ILQ-TR

Note: This is a list of Ordering Part Numbers (OPNs) as are found in product datasheets. Customers may track additional part number variants in their systems, so please consider this a base part list.

Production Shipment Schedule:

Product assembled at the new assembly site, with the new material BOM and in MSL3 pack is planned to ship no sooner than March 15, 2017 unless customers provide written acceptance of the new product.

During a transition period, customers may see shipments with either location while any existing inventory of parts is depleted.

Qualification Data:

Qualification Reports will be available in December 2016.



Microsemi Corporate Headquarters
One Enterprise, Aliso Viejo, CA 92656 USA
Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996
E-mail: sales.support@microsemi.com
www.microsemi.com

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Samples Availability:

Samples are available upon request.

Please contact your local Microsemi representative to place sample orders.

Contact Information:

Communications Products Group

CMPG.quality@microsemi.com

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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CHANGE APPROVAL SUPPLEMENT

Customer Acknowledgement / Approval for Product/Process Change Notification No: 157021

Microsemi Corporation intends to implement this change 90 days after this notification. Acknowledgement of your company's acceptance of this change is requested per contractual agreement. Response within 30 days is required.

Accepted

Rejected

Signature

Date

Name

Title

Please enter rationale for rejection, if applicable: _____



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Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996
E-mail: sales.support@microsemi.com
www.microsemi.com

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